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<u>AMENDMENTS TO THE CLAIMS:</u>

Please cancel claim 17 without prejudice or disclaimer.

(Currently amended) A group III nitride compound semiconductor light-emitting device, comprising:

a semiconductor laminate portion formed on a substrate and including a light-emitting layer; and

a reflection surface provided on a layer of said semiconductor laminate portion said substrate and disposed so as to be opposite to a side surface of said light-emitting layer,

wherein a predetermined distance is provided between said semiconductor laminate portion and said reflection surface.

- (Previously presented) A group III nitride compound semiconductor light-emitting 2. device according to claim 1, wherein said reflection surface reflects light emitted from said side surface of said semiconductor laminate portion into a direction of an optical axis of said light-emitting device.
- (Previously presented) A group III nitride compound semiconductor light-emitting 3. device according to claim 1, wherein said predetermined distance comprises a distance between said reflection surface and said side surface of said semiconductor laminate portion which is in a range of from 0.1 to 10µm.
- (Previously presented) A group III nitride compound semiconductor light-emitting 4. device according to claim 1, further comprising:

an n pad electrode,

wherein said reflection surface comprises a material which is the same as that of said n pad electrode.

(Previously presented) A group III nitride compound semiconductor light-emitting 5. device according to claim 4, further comprising:

a second reflection surface comprising a portion of said n pad electrode opposite to

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said side surface of said semiconductor laminate portion.

- 6. (Previously presented) A group III nitride compound semiconductor light-emitting device according to claim 4, wherein said reflection surface is formed on an n-type semiconductor layer which is formed by etching to a first depth, and said n pad electrode is formed on said n-type semiconductor layer which is formed by etching to a second depth shallower than said first depth.
- (Original) A group II nitride compound semiconductor light-emitting device according to claim 4, wherein said reflection surface is formed integrally with said n pad electrode.
- 8-14. (Canceled)
- 15. (Previously presented) A group III nitride compound semiconductor light-emitting device according to claim 1, wherein said predetermined distance comprises a distance between said reflection surface and said side surface of said semiconductor laminate portion which is in a range of 0.2 μ m to 7 μ m.
- 16. (Previously presented) A group III nitride compound semiconductor light-emitting device according to claim 1, wherein said predetermined distance comprises a distance between said reflection surface and said side surface of said semiconductor laminate portion which is in a range of $0.3~\mu m$ to $5~\mu m$.
- 17. (Canceled)
- 18. (Previously presented) A group III nitride compound semiconductor light-emitting device according to claim 1, wherein an upper surface of said reflection surface is elevated higher than said light-emitting layer.
- 19. (Previously presented) A group III nitride compound semiconductor light-emitting

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device according to claim 1, wherein said reflection surface comprises a curved reflection surface.

20-22. (Canceled)

- 23. (Previously presented) A group III nitride compound semiconductor light-emitting device according to claim 1, wherein said reflection surface reflects light emitted from said side surface of said semiconductor laminate portion
- 24. (Previously presented) A group III nitride compound semiconductor light-emitting device according to claim 1, wherein said reflection surface comprises a shape for reflecting light in a direction of an optical axis for said light-emitting device.
- 25. (Previously presented) A group III nitride compound semiconductor light-emitting device according to claim 1, wherein said predetermined distance comprises a distance between said reflection surface and said side surface of said semiconductor laminate portion which is no greater than 10µm.
- 26. (Previously presented) A group III nitride compound semiconductor light-emitting device according to claim 1, wherein said direction of an optical axis comprises a direction of a center axis of said device.
- 27. (Previously presented) A group III nitride compound semiconductor light-emitting device according to claim 1, further comprising:

an n-pad electrode formed on said semiconductor laminate portion, said reflection surface comprising a side surface of said n-pad electrode having a shape for reflecting light in a direction of an optical axis for said light-emitting device.

28. (Previously presented) A group III nitride compound semiconductor light-emitting device according to claim 1, wherein said reflection surface is formed around a circumference of said light-emitting layer.

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- (Previously presented) A group III nitride compound semiconductor light-emitting 29. device according to claim 1, wherein at least a portion of said reflection surface is formed near a plane of said light-emitting layer.
- (Previously presented) A group III nitride compound semiconductor light-emitting 30. device according to claim 1, wherein said reflection surface is disposed so as to be transversely opposite to a side surface of said light-emitting layer.
- (Previously presented) A group III nitride compound semiconductor light-emitting 31. device according to claim 1, wherein said reflection surface comprises a thickness of at least $0.7 \mu m$.
- 32. (Canceled)
- (Withdrawn) A group III nitride compound semiconductor light-emitting device 33. according to claim 1, further comprising:

a reflective material formed on said substrate and comprising said reflection surface.

- (Withdrawn Currently amended) A group III nitride compound semiconductor light-34. emitting device according to claim 33, wherein said [[a]] reflective material comprises an electrically conductive material.
- (Withdrawn) A group III nitride compound semiconductor light-emitting device 35. according to claim 33, wherein said semiconductor laminate portion comprises an n-type semiconductor layer, said reflective material being formed on a same layer as said n-type semiconductor layer.
- (Withdrawn) A group III nitride compound semiconductor light-emitting device 36. according to claim 1, wherein said side surface comprises a vertical side surface.

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(Withdrawn) A group III nitride compound semiconductor light-emitting device, 37. comprising:

a semiconductor laminate portion formed on a substrate and comprising:

an n-type semiconductor layer; and

a light-emitting layer formed on said n-type semiconductor layer; and an electrically conductive material formed on a same layer as said n-type semiconductor layer and comprising a reflection surface disposed so as to be opposite to a vertical side surface of said light-emitting layer,

wherein a distance provided between said semiconductor laminate portion and said reflection surface is no greater than 10 µm.